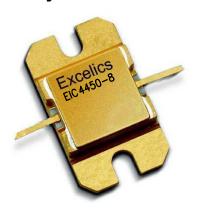




4.40-5.00GHz 8-Watt Internally Matched Power FET

FEATURES

- 4.40-5.00GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +39.5 dBm Output Power at 1dB Compression
- 10.5 dB Power Gain at 1dB Compression
- 35% Power Added Efficiency
- -46 dBc IM3 at PO = 28.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}



ELECTRICAL CHARACTERISTICS (T_a = 25°C)



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compression $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	38.5	39.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$	9.5	10.5		dB
ΔG	Gain Flatness $f = 4.4-5.0GHz$ $V_{DS} = 10 \text{ V}, I_{DSQ} \approx 2200\text{mA}$			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 2200mA		35		%
Id _{1dB}	Drain Current at 1dB Compression f = 4.4-5.0GHz		2300	2600	mA
IM3	Output 3rd Order Intermodulation Distortion $\Delta f = 10 \text{ MHz } 2\text{-Tone Test}$; Pout = 28.5 dBm S.C.L ² $V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$ f =5.0GHz	-43	-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		4000	5000	mA
V_P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 40 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		3.5	4.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

2. S.C.L. = Single Carrier Level.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²	
Vds	Drain-Source Voltage	15V	10V	
Vgs	Gate-Source Voltage	-5V	-4V	
Igf Forward Gate Current		96mA	28.8mA	
lgr	Reverse Gate Current	-19.2mA	-4.8mA	
Pin	Pin Input Power		@ 3dB Compression	
Tch Channel Temperature		175C	175C	
Tstg Storage Temperature		-65C to +175C	-65C to +175C	
Pt Total Power Dissipation		37.5W	37.5W	

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{3.} Overall Rth depends on case mounting.

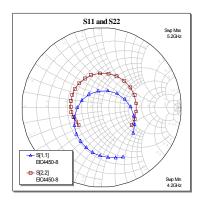
^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.

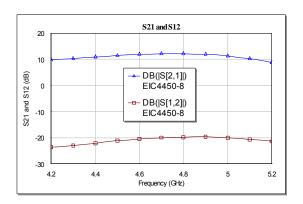


4.40-5.00GHz 8-Watt Internally Matched Power FET

PERFORMANCE DATA

Typical S-Parameters (T= 25°C, 50Ω system, de-embedded to edge of package) V_{DS} = 10 V, I_{DSQ} ≈ 2200mA





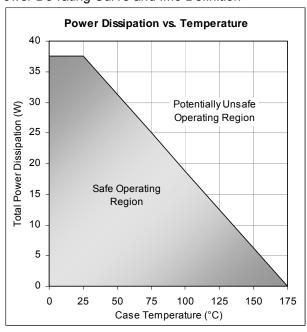
FREQ	S11		S21		S12		S22	
(GHz)	MAG	ANG	MAG	ANG	MAG	ANG	MAG	ANG
4.0	0.7503	-37.83	2.703	97.27	0.0555	43.87	0.3563	-105.99
4.2	0.6786	-66.68	3.0738	66.41	0.0662	11.77	0.3648	-142.14
4.4	0.5779	-101.09	3.5153	32.39	0.0788	-21.55	0.3889	178.7
4.6	0.4132	-146.28	3.9355	-6.5	0.0954	-60.58	0.4149	132.78
4.8	0.2292	134.17	4.0571	-50.3	0.1033	-105.97	0.4326	78.67
5.0	0.308	19.37	3.6482	-96.93	0.0989	-153.5	0.4399	20.6
5.2	0.5127	-39.49	2.78	-140.48	0.0854	160.93	0.4385	-30.72
5.4	0.6658	-77.6	1.9617	-177.01	0.0678	119.63	0.4493	-70.46
5.6	0.7585	-107.39	1.3733	153.13	0.0532	81.38	0.4784	-98.19
5.8	0.8058	-133.11	1.0074	126.36	0.0414	46.84	0.5605	-121.4
6.0	0.8356	-155.36	0.7453	101.98	0.0333	18.09	0.6098	-141.51

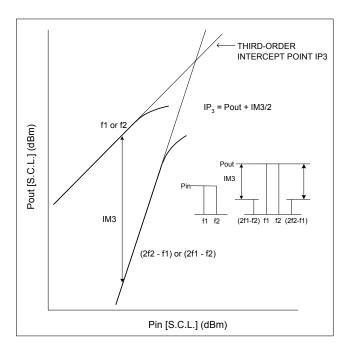




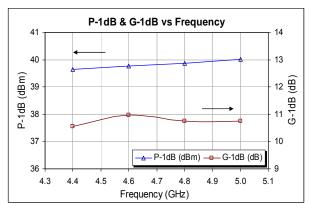
4.40-5.00GHz 8-Watt Internally Matched Power FET

Power De-rating Curve and IM3 Definition

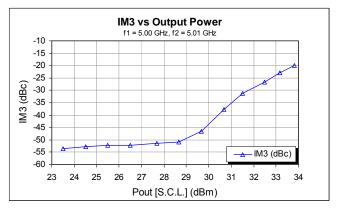




Typical Power Data (V_{DS} = 10 V, I_{DSQ} = 2200 mA)



Typical IM3 Data ($V_{DS} = 10 \text{ V}$, $I_{DSQ} \approx 65\% \text{ IDSS}$)



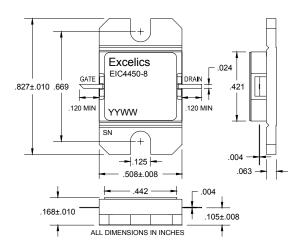


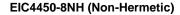
4.40-5.00GHz 8-Watt Internally Matched Power FET

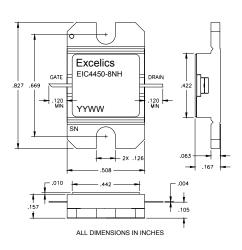
PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

EIC4450-8 (Hermetic)









Caution! ESD sensitive device.



Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	$IM_3 (min)^2$
EIC4450-8	Hermetic	Industrial	4.40-5.00GHz	38.5	-43
EIC4450-8NH	Non-Hermetic	Industrial	4.40-5.00GHz	38.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness